

FM820-CF THRU FM8200-CF**List**

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FM820-CF THRU FM8200-CF

8.0A Surface Mount Schottky Barrier Rectifiers 50V-200V

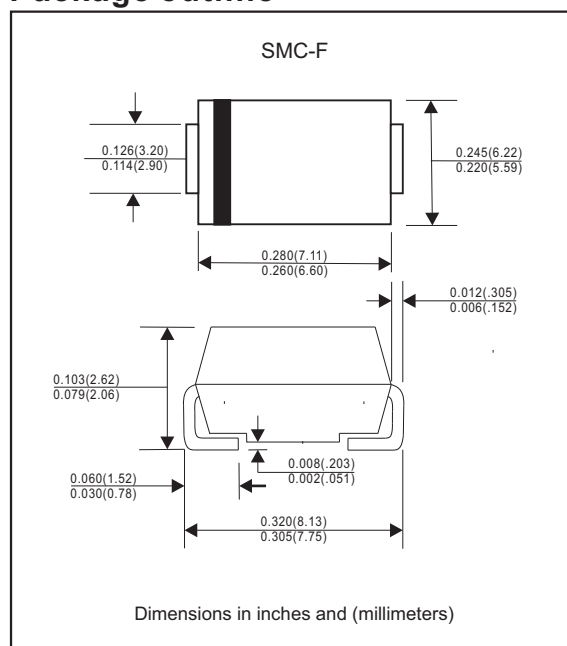
Features

- Low power loss, high efficiency.
- High current capability, low forward voltage drop.
- High forward surge current capability.
- Silicon epitaxial planar chip, metal silicon junction.
- Lead-free parts meet RoHS requirements.
- Suffix "-H" indicates Halogen free parts, ex. FM820-CF-H.

Mechanical data

- Epoxy: UL94-V0 rated flame retardant
- Case : Molded plastic, DO-214AB / SMC-F
- Terminals : Solder plated, solderable per MIL-STD-750, Method 2026
- Polarity : Indicated by cathode band
- Mounting Position : Any
- Weight : Approximated 0.23 gram

Package outline



Maximum ratings (AT $T_A=25^{\circ}\text{C}$ unless otherwise noted)

Parameter	Symbols	FM820-CF	FM840-CF	FM860-CF	FM880-CF	FM8100-CF	FM8150-CF	FM8200-CF	Units
Maximum repetitive peak reverse voltage	V_{RRM}	20	40	60	80	100	150	200	V
Maximum RMS voltage	V_{RMS}	14	28	42	56	70	105	140	V
Maximum DC blocking voltage	V_{DC}	20	40	60	80	100	150	200	V
Maximum average forward rectified current at T_L (see fig. 1)	I_O	8.0							A
Peak forward surge current, 8.3ms single half-sine-wave (JEDEC method)	I_{FSM}	150.0							A
Operating junction temperature range	T_J	-55 to +150							$^{\circ}\text{C}$
Storage temperature range	T_{STG}	-55 to +150							$^{\circ}\text{C}$

Electrical characteristics (AT $T_A=25^{\circ}\text{C}$ unless otherwise noted)

Parameter	Symbols	FM820-CF	FM840-CF	FM860-CF	FM880-CF	FM8100-CF	FM8150-CF	FM8200-CF	Units
Maximum forward voltage at $I_F=8.0A$	V_F	0.55		0.70	0.85		0.95		V
Maximum reverse current at $T_A=25^{\circ}C$ at rated DC blocking voltage $T_A=125^{\circ}C$	I_R	0.5 50			0.05 10				mA

Thermal characteristics

Parameter	Symbols	FM820-CF	FM840-CF	FM860-CF	FM880-CF	FM8100-CF	FM8150-CF	FM8200-CF	Units
Typical thermal resistance junction to ambient	$R_{\theta JA}$	47.0							$^{\circ}\text{C/W}$

Rating and characteristic curves (FM820-CF THRU FM8200-CF)

Fig.1 FORWARD CURRENT DERATING CURVE

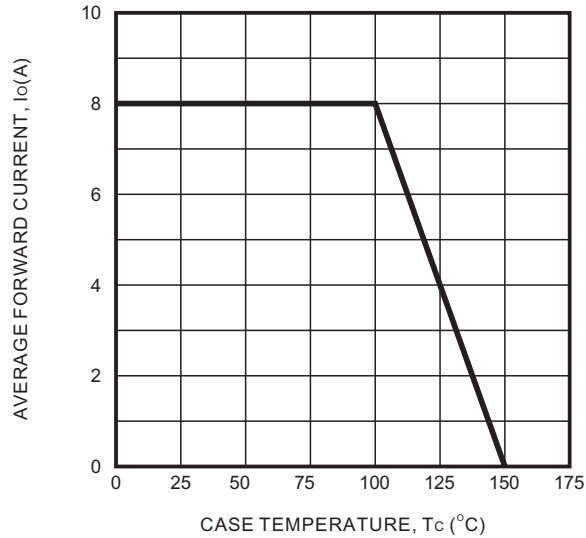


Fig.2 TYPICAL FORWARD CHARACTERISTICS

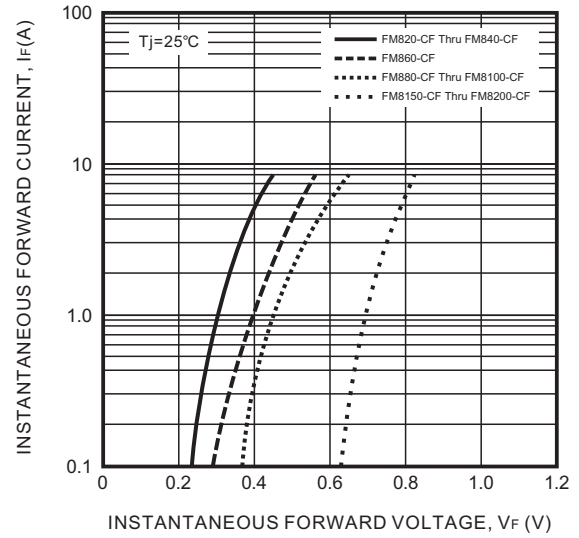


Fig.3 MAXIMUM NON-REPETITIVE PEAK FORWARD SURGE CURRENT

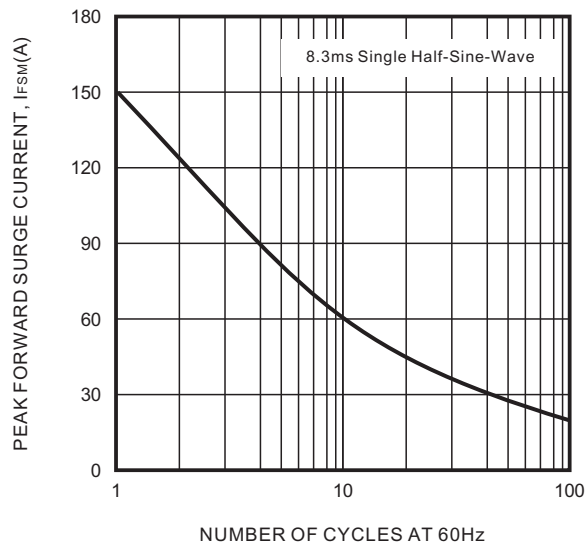
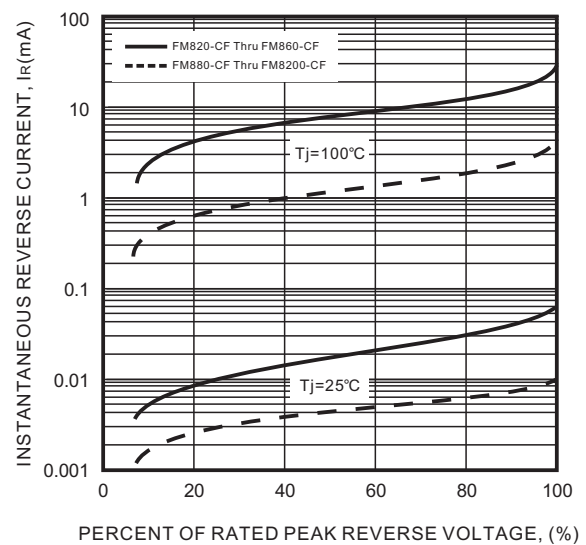


Fig.4 TYPICAL REVERSE CHARACTERISTICS

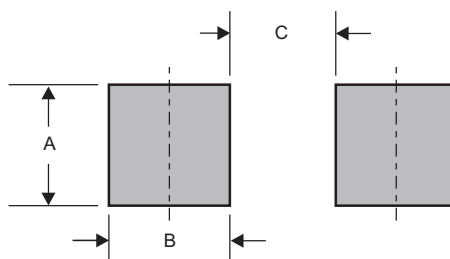


FM820-CF THRU FM8200-CF**Pinning information**

Pin	Simplified outline	Symbol
Pin1 cathode Pin2 anode		

Marking

Type number	Marking code
FM820-CF	SS82
FM840-CF	SS84
FM860-CF	SS86
FM880-CF	SS88
FM8100-CF	SS810
FM8150-CF	SS815
FM8200-CF	SS820

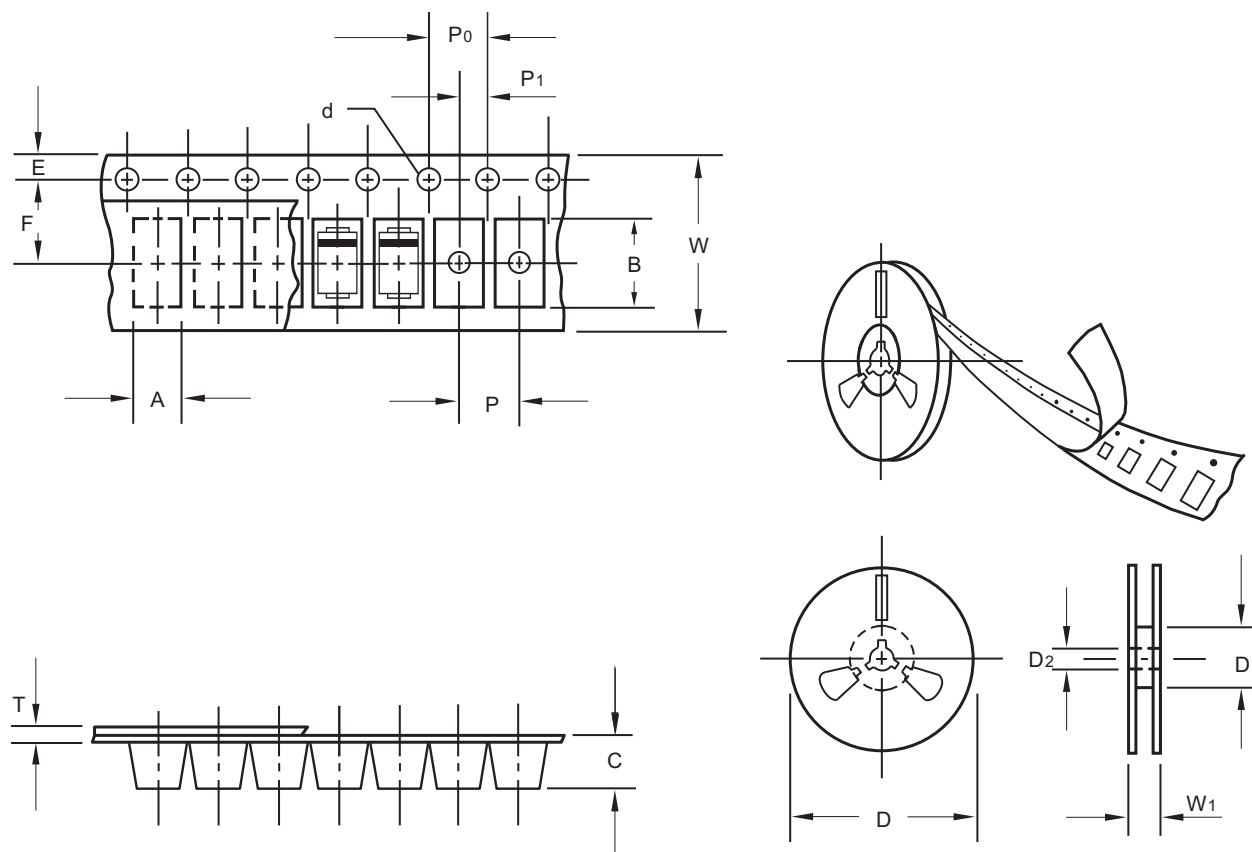
Suggested solder pad layout

Dimensions in inches and (millimeters)

PACKAGE	A	B	C
SMC-F	0.132 (3.30)	0.100 (2.50)	0.176(4.40)

FM820-CF THRU FM8200-CF

Packing information



unit:mm

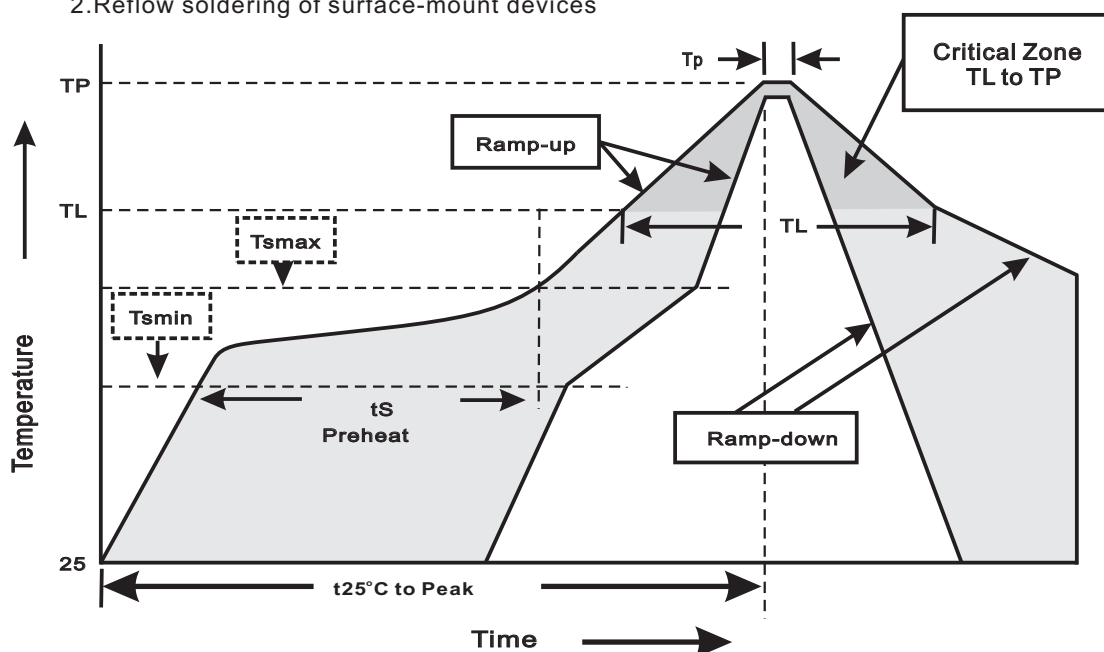
Item	Symbol	Tolerance	SMC-F
Carrier width	A	0.15	6.00
Carrier length	B	0.2	8.25
Carrier depth	C	0.1	2.36
Sprocket hole	d	0.1	1.50
13" Reel outside diameter	D	2.0	330.00
13" Reel inner diameter	D ₁	min	50.00
7" Reel outside diameter	D	2.0	178.00
7" Reel inner diameter	D ₁	min	62.00
Feed hole diameter	D ₂	0.5	13.00
Sprocket hole position	E	0.1	1.75
Punch hole position	F	0.1	7.50
Punch hole pitch	P	0.1	8.00
Sprocket hole pitch	P ₀	0.1	4.00
Embossment center	P ₁	0.1	2.00
Overall tape thickness	T	0.1	0.23
Tape width	W	0.3	16.00
Reel width	W ₁	1.0	18.00

Note: Devices are packed in accordance with EIA standard RS-481-A and specifications listed above.

Reel packing

PACKAGE	REEL SIZE	REEL (pcs)	COMPONENT SPACING (m/m)	BOX (pcs)	INNER BOX (m/m)	REEL DIA, (m/m)	CARTON SIZE (m/m)	CARTON (pcs)	APPROX. GROSS WEIGHT (kg)
SMC-F	13"	3,000	8.0	6,000	338*338*38	330	365*365*360	48,000	18.8

1.Storage environment: Temperature=5°C~40°C Humidity=55%±25%
2.Reflow soldering of surface-mount devices



Profile Feature	Soldering Condition
Average ramp-up rate(T_L to T_P)	$<3^{\circ}\text{C}/\text{sec}$
Preheat -Temperature Min(T_{min}) -Temperature Max(T_{max}) -Time(min to max)(t_s)	150°C 200°C $60\sim 120\text{sec}$
T_{max} to T_L -Ramp-upRate	$<3^{\circ}\text{C}/\text{sec}$
Time maintained above: -Temperature(T_L) -Time(t_L)	217°C $60\sim 260\text{sec}$
Peak Temperature(T_P)	$255^{\circ}\text{C}-0/+5^{\circ}\text{C}$
Time within 5°C of actual Peak Temperature(t_P)	$10\sim 30\text{sec}$
Ramp-down Rate	$<6^{\circ}\text{C}/\text{sec}$
Time 25°C to Peak Temperature	$<6\text{minutes}$

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High reliability test capabilities

Item Test	Conditions	Reference
1. Solder Resistance	at $260 \pm 5^\circ\text{C}$ for $10 \pm 2\text{sec.}$ immerse body into solder $1/16" \pm 1/32"$	MIL-STD-750D METHOD-2031
2. Solderability	at $245 \pm 5^\circ\text{C}$ for 5 sec.	MIL-STD-202F METHOD-208
3. High Temperature Reverse Bias	$V_R = 80\%$ rate at $T_J = 150^\circ\text{C}$ for 168 hrs.	MIL-STD-750D METHOD-1038
4. Forward Operation Life	Rated average rectifier current at $T_A = 25^\circ\text{C}$ for 500hrs.	MIL-STD-750D METHOD-1027
5. Intermittent Operation Life	$T_A = 25^\circ\text{C}$, $I_F = I_O$ On state: power on for 5 min. off state: power off for 5 min. on and off for 500 cycles.	MIL-STD-750D METHOD-1036
6. Pressure Cooker	$15P_{SIG}$ at $T_A = 121^\circ\text{C}$ for 4 hrs.	JESD22-A102
7. Temperature Cycling	-55°C to $+125^\circ\text{C}$ dwelled for 30 min. and transferred for 5min. total 10 cycles.	MIL-STD-750D METHOD-1051
8. Forward Surge	8.3ms single half sine-wave , one surge.	MIL-STD-750D METHOD-4066-2
9. Humidity	at $T_A = 85^\circ\text{C}$, RH=85% for 1000hrs.	MIL-STD-750D METHOD-1021
10. High Temperature Storage Life	at 150°C for 1000 hrs.	MIL-STD-750D METHOD-1031